### NCE N-Channel Enhancement Mode Power MOSFET

### **General Features**

•  $V_{DS} = 60V, I_D = 0.3A$ 

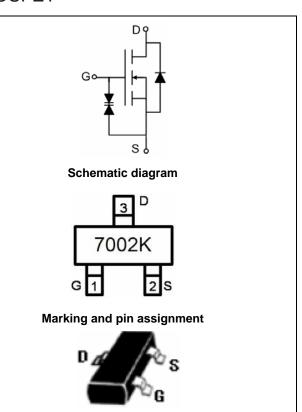
 $R_{DS(ON)}$  < 3 $\Omega$  @  $V_{GS}$ =4.5V

 $R_{DS(ON)}$  < 2.2 $\Omega$  @  $V_{GS}$ =10V

- High power and current handing capability
- Lead free product is acquired
- Surface mount package
- ESD Rating: HBM ≥1500V

### **Application**

- Direct logic-level interface: TTL/CMOS
- Drivers: relays, solenoids, lamps, hammers, display, memories, transistors, etc.
- Battery operated systems
- Solid-state relays



SOT-23 top view

### **Package Marking And Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
7002K	2N7002K	SOT-23	Ø180mm	8 mm	3000 units

### Absolute Maximum Ratings (T<sub>A</sub>=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V <sub>DS</sub>	60	V	
Gate-Source Voltage		V <sub>GS</sub>	±20	V	
Continuous Prain Current /T =150°C	T <sub>A</sub> =25℃		0.3	А	
Continuous Drain Current (T <sub>J</sub> =150℃)	T <sub>A</sub> =100°C	I <sub>D</sub>	0.19		
Drain Current-Pulsed (Note 1)	I <sub>DM</sub>	0.8	Α		
Maximum Power Dissipation		P <sub>D</sub>	0.35	W	
Operating Junction and Storage Temperature Range		$T_{J}$ , $T_{STG}$	-55 To 150	$^{\circ}$ C	

### **Thermal Characteristic**

Thermal Resistance, Junction-to-Ambient (Note 2) R <sub>0JA</sub> 350 °C/W
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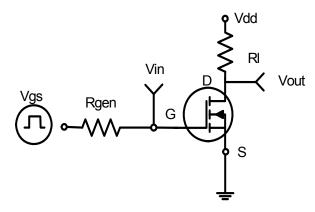
## Electrical Characteristics ( $T_A$ =25 $^{\circ}$ C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	60	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =60V,V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	$V_{GS}$ =±10V, $V_{DS}$ =0V	-	-	±1	uA
Gate-body Leakage Guirent	IGSS	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V	-		±10	uA
On Characteristics (Note 3)				•		
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS},I_{D}=250\mu A$	0.7	1.3	1.9	V
Drain-Source On-State Resistance	В	V <sub>GS</sub> =4.5V, I <sub>D</sub> =0.2A	-	1.95	3	Ω
Diair-Source Oil-State Resistance	$R_{DS(ON)}$	V <sub>GS</sub> =10V, I <sub>D</sub> =0.3A	-	1.8	2.2	Ω
Forward Transconductance	<b>g</b> fs	V <sub>DS</sub> =10V,I <sub>D</sub> =0.2A	0.1	-	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C <sub>lss</sub>	$V_{DS}$ =25V, $V_{GS}$ =0V,	10	21	50	PF
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> -23V, V <sub>GS</sub> -0V, F=1.0MHz	-	11	25	PF
Reverse Transfer Capacitance	$C_{rss}$	F = 1.01VII 12	-	4.2	5	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t <sub>d(on)</sub>		-	10	-	nS
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =30 $V$ , $I_D$ =0.2 $A$	-	50	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS}$ =10 $V$ , $R_{GEN}$ =10 $\Omega$	-	17	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	10	-	nS
Total Gate Charge	ate Charge $Q_{g} \hspace{1cm} V_{DS}\text{=}10V, I_{D}\text{=}0.3A, \\ V_{GS}\text{=}4.5V$		-	1.7	3	nC
Drain-Source Diode Characteristics	,			•		•
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =0.2A	-	-	1.2	V
Diode Forward Current (Note 2)	Is		-	-	0.3	Α

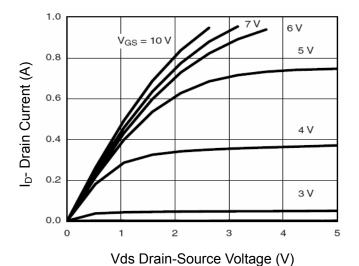
### Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production

### **Typical Electrical And Thermal Characteristics**



**Figure 1:Switching Test Circuit** 



**Figure 3 Output Characteristics** 

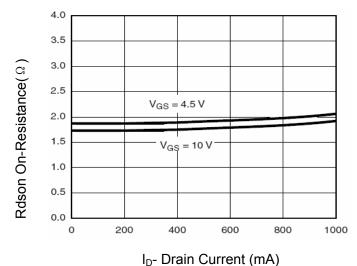


Figure 5 Drain-Source On-Resistance

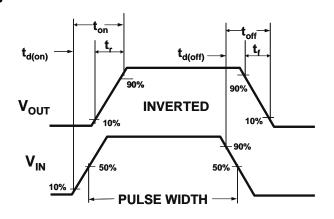
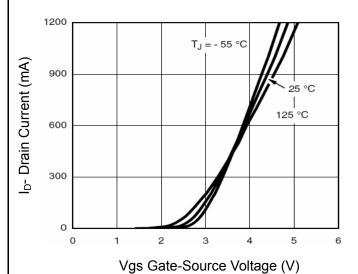
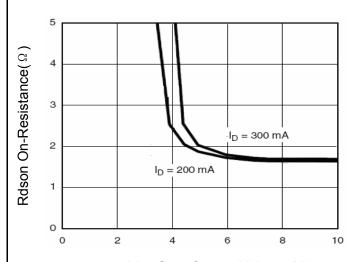


Figure 2:Switching Waveforms

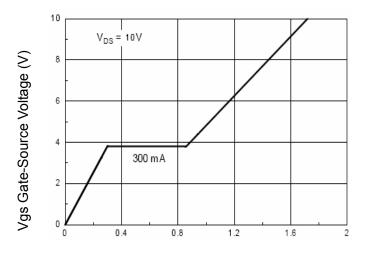


**Figure 4 Transfer Characteristics** 



Vgs Gate-Source Voltage (V) Figure 6 Rdson vs Vgs





Qg Gate Charge (nC) Figure 7 Gate Charge

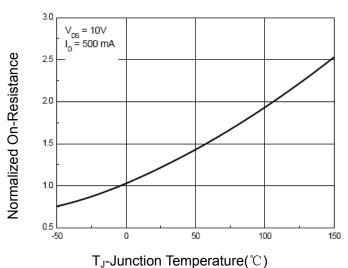


Figure 9 Drain-Source On-Resistance

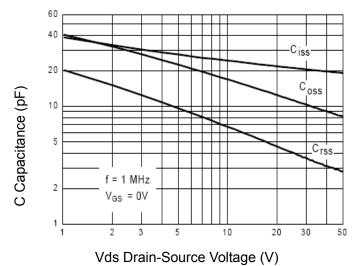
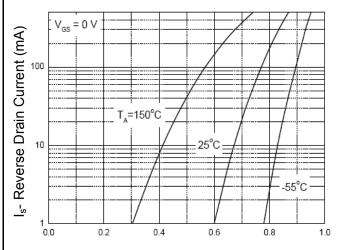
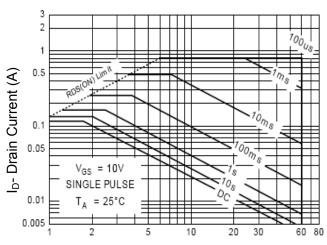


Figure 11 Capacitance vs Vds



Vsd Source-Drain Voltage (V)

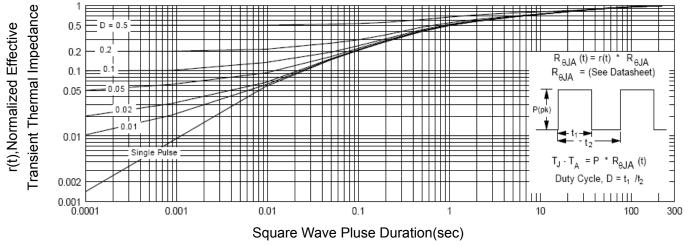




Vds Drain-Source Voltage (V)

Figure 10 Safe Operation Area

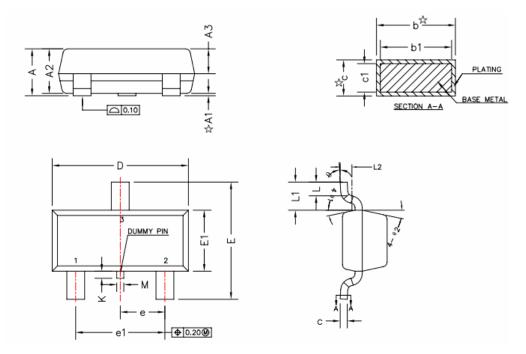




**Figure 12 Normalized Maximum Transient Thermal Impedance** 



# **SOT-23 Package Information**



Symbol	Millimeters			
Symbol	Min.	Max.		
Α	0.89	1.12		
A1	0.01	0.10		
A2	0.88	1.02		
A3	0.43	0.63		
b	0.36	0.50		
b1	0.35	0.45		
С	0.14	0.20		
c1	0.14	0.16		
D	2.80	3.00		
E	2.35	2.64		
E1	1.20	1.40		
е	0.90	1.00		
e1	1.80	2.00		
L	0.40	0.60		
L1	0.6REF			
L2	0.25BSC			
M	0.10	0.25		
K	0.00	0.25		
θ	0°	8°		
θ1	10°	14°		
θ2	10°	14°		

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